

Title (en)

METHOD FOR MAKING CONTACT WITH PARTIALLY CONDUCTIVE TEXTILE SEMIFINISHED PRODUCTS

Title (de)

VERFAHREN ZUR KONTAKTIERUNG VON PARTIELL LEITFÄHIGEN TEXTILEN HALBZEUGEN

Title (fr)

PROCEDE DE MISE EN CONTACT DES DEMI-PRODUITS TEXTILES PARTIELLEMENT CONDUCTEURS

Publication

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Application

EP 06762886 A 20060728

Priority

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Abstract (en)

[origin: WO2007014718A1] Method for electrically connecting conductive threads (conducting threads) (40) to any desired number of connection points on a textile semifinished product (5) using a connection element which is preferably in the form of a printed circuit board, wherein the following steps are provided: insertion of the printed circuit board in a correspondingly shaped cutout in a supporting plate of a tool having upwardly pointing connection points (122) of the printed circuit board (12); arranging the semifinished product (5) on the printed circuit board (12) such that a connection point, to be connected, on the semifinished product (5) comes to lie in the region of the connection points of the printed circuit board (12); fixing, preferably by means of fixedly clamping, the semifinished product adjacent to and on one side of the connection points of the printed circuit board; preferably extending the semifinished product (5) in the longitudinal direction or in the direction of the profile of the conducting threads; fixedly clamping the semifinished product in a region opposite the first fixed clamping region and adjacent to the desired connection point; soldering the exposed conducting threads (40) to the connection points on the printed circuit board (12).

IPC 8 full level

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